

**flowPIM 1 3rd gen**
**1200V / 35A**
**Features**

- 3- rectifier, BRC, Inverter, NTC
- Very compact housing, easy to route
- IGBT4 / EmCon4 technology for low saturation losses and improved EMC behaviour
- High performance with AlN substrate

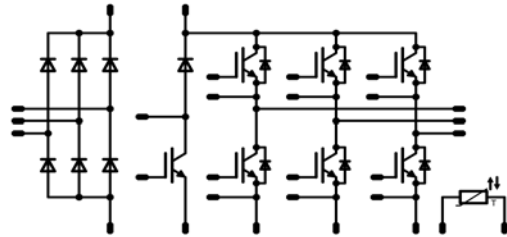
**Target Applications**

- Motor Drives
- Power Generation

**Types**

- V23990-P580-A46-PM

**flowPIM1 housing**

**Schematic**


## Maximum Ratings

 T<sub>j</sub>=25°C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
<b>Input Rectifier Diode</b>				
Peak repetitive reverse voltage	V <sub>RRM</sub>		1600	V
Forward current per diode	I <sub>FAV</sub>	DC current T <sub>n</sub> =80°C	50	A
Surge forward current	I <sub>FSM</sub>	t <sub>p</sub> =10ms T <sub>j</sub> =45°C	320	A
I <sup>2</sup> t-value	I <sup>2</sup> t		510	A <sup>2</sup> s
Power dissipation per diode	P <sub>tot</sub>	T <sub>j</sub> =T <sub>jmax</sub> T <sub>n</sub> =80°C	82	W
Maximum junction temperature	T <sub>jmax</sub>		150	°C
<b>Inverter Transistor</b>				
Collector-emitter break down voltage	V <sub>CE</sub>		1200	V
DC collector current	I <sub>C</sub>	T <sub>j</sub> =T <sub>jmax</sub> T <sub>n</sub> =80°C	49	A
Repetitive peak collector current	I <sub>Cpulse</sub>	t <sub>p</sub> limited by T <sub>jmax</sub>	105	A
Power dissipation per IGBT	P <sub>tot</sub>	T <sub>j</sub> =T <sub>jmax</sub> T <sub>n</sub> =80°C	152	W
Gate-emitter peak voltage	V <sub>GE</sub>		±20	V
Short circuit ratings	t <sub>SC</sub> V <sub>CC</sub>	T <sub>j</sub> ≤150°C V <sub>GE</sub> =15V	10 800	µs V
Maximum junction temperature	T <sub>jmax</sub>		175	°C

## Maximum Ratings

 $T_j=25^{\circ}\text{C}$ , unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
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### Inverter Diode

Peak repetitive reverse voltage	$V_{RRM}$	$T_j=25^{\circ}\text{C}$	1200	V
DC forward current	$I_F$	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	50	A
Repetitive peak forward current	$I_{FRM}$	$t_p$ limited by $T_{jmax}$	70	A
Power dissipation per diode	$P_{tot}$	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	121	W
Maximum junction temperature	$T_{jmax}$		175	$^{\circ}\text{C}$

### Brc Transistor

Collector-emitter break down voltage	$V_{CE}$		1200	V
DC collector current	$I_C$	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	40	A
Repetitive peak collector current	$I_{Cpuls}$	$t_p$ limited by $T_{jmax}$	75	A
Power dissipation per IGBT	$P_{tot}$	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	133	W
Gate-emitter peak voltage	$V_{GE}$		$\pm 20$	V
Short circuit ratings	$t_{SC}$ $V_{CC}$	$T_j \leq 150^{\circ}\text{C}$ $V_{GE} = 15\text{V}$	10 800	$\mu\text{s}$ V
Maximum junction temperature	$T_{jmax}$		175	$^{\circ}\text{C}$

### Brc Diode

Peak repetitive reverse voltage	$V_{RRM}$	$T_j=25^{\circ}\text{C}$	1200	V
DC forward current	$I_F$	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	20	A
Repetitive peak forward current	$I_{FRM}$	$t_p$ limited by $T_{jmax}$	20	A
Power dissipation per diode	$P_{tot}$	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	59	W
Maximum junction temperature	$T_{jmax}$		175	$^{\circ}\text{C}$

### Thermal Properties

Storage temperature	$T_{stg}$		-40...+125	$^{\circ}\text{C}$
Operation temperature under switching condition	$T_{op}$		-40...+( $T_{jmax} - 25$ )	$^{\circ}\text{C}$

### Insulation Properties

Insulation voltage	$V_{is}$	$t=2\text{s}$ DC voltage	4000	V
Creepage distance			min 12.7	mm
Clearance			min 12.7	mm

**Characteristic Values**

Parameter	Symbol	Conditions					Value			Unit
		$V_{GE}[V]$ or $V_{GS}[V]$	$V_r[V]$ or $V_{CE}[V]$ or $V_{DS}[V]$	$I_c[A]$ or $I_F[A]$ or $I_D[A]$	$T_j$	Min	Typ	Max		
<b>Input Rectifier Diode</b>										
Forward voltage	$V_F$				50	$T_j=25^\circ C$ $T_j=125^\circ C$	0.8	1.29 1.24	1.6	V
Threshold voltage (for power loss calc. only)	$V_{to}$				50	$T_j=25^\circ C$ $T_j=125^\circ C$		0.93 0.82		V
Slope resistance (for power loss calc. only)	$r_t$				50	$T_j=25^\circ C$ $T_j=125^\circ C$		0.007 0.009		$\Omega$
Reverse current	$I_r$			1500		$T_j=25^\circ C$ $T_j=125^\circ C$			0.02 2	mA
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal foil thickness=76um						0.85		K/W
Thermal resistance chip to case per chip	$R_{thJC}$	Kunze foil KU-ALF5						N/A		
<b>Inverter Transistor</b>										
Gate emitter threshold voltage	$V_{GE(th)}$	VCE=VGE			0.0012	$T_j=25^\circ C$ $T_j=150^\circ C$	5	5.8	6.5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		35	$T_j=25^\circ C$ $T_j=150^\circ C$	1.6	1.95 2.39	2.3	V
Collector-emitter cut-off current incl. diode	$I_{CES}$		0	1200		$T_j=25^\circ C$ $T_j=150^\circ C$			0.01	mA
Gate-emitter leakage current	$I_{GES}$		20	0		$T_j=25^\circ C$ $T_j=150^\circ C$			200	nA
Integrated gate resistor	$R_{gint}$							-		$\Omega$
Turn-on delay time	$t_{d(on)}$	Rgoff=16 $\Omega$ Rgon=16 $\Omega$	$\pm 15$	600	35	$T_j=25^\circ C$		92		ns
Rise time	$t_r$					$T_j=150^\circ C$		91.6		
Turn-off delay time	$t_{d(off)}$					$T_j=25^\circ C$		18		
Fall time	$t_f$					$T_j=150^\circ C$		23.4		
Turn-on energy loss per pulse	$E_{on}$					$T_j=25^\circ C$		213		
Turn-off energy loss per pulse	$E_{off}$	$T_j=150^\circ C$		274						
Input capacitance	$C_{ies}$							1950		pF
Output capacitance	$C_{oss}$	f=1MHz	0	25		$T_j=25^\circ C$		155		
Reverse transfer capacitance	$C_{rss}$							115		
Gate charge	$Q_{Gate}$	Vcc=960V	$\pm 15$		35	$T_j=25^\circ C$		270		nC
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal foil thickness=76um						0.62		K/W
Thermal resistance chip to case per chip	$R_{thJC}$	Kunze foil KU-ALF5						N/A		
<b>Inverter Diode</b>										
Diode forward voltage	$V_F$				35	$T_j=25^\circ C$ $T_j=150^\circ C$	1	1.83 1.8	2.2	V
Peak reverse recovery current	$I_{RRM}$					$T_j=25^\circ C$ $T_j=150^\circ C$		68.9 78.7		A
Reverse recovery time	$t_{rr}$	Rgoff=16 $\Omega$	$\pm 15$	600	35	$T_j=25^\circ C$		150		ns
Reverse recovered charge	$Q_{rr}$					$T_j=150^\circ C$		277		
Peak rate of fall of recovery current	$di(rec)max/dt$					$T_j=25^\circ C$		3.93		
Reverse recovered energy	$E_{rec}$	$T_j=150^\circ C$		7.47						
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal foil thickness=76um						0.78		K/W
Thermal resistance chip to case per chip	$R_{thJC}$	Kunze foil KU-ALF5						N/A		

**Characteristic Values**

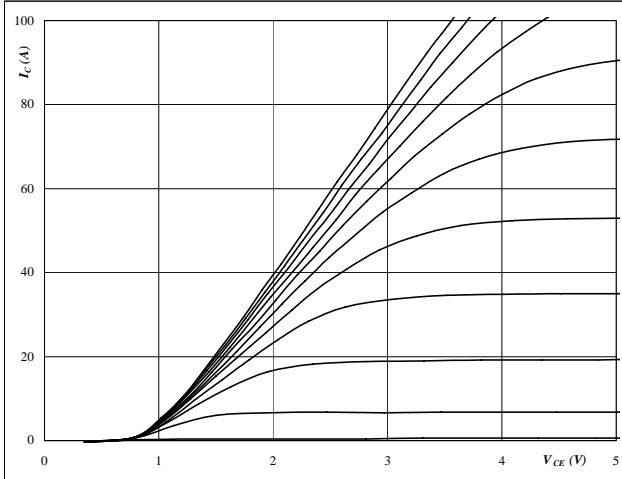
Parameter	Symbol	Conditions					Value			Unit	
		$V_{GE}[V]$ or $V_{GS}[V]$	$V_r[V]$ or $V_{CE}[V]$ or $V_{DS}[V]$	$I_c[A]$ or $I_F[A]$ or $I_D[A]$	$T_j$	Min	Typ	Max			
<b>Brc Transistor</b>											
Gate emitter threshold voltage	$V_{GE(th)}$	VCE=VGE			0.00085	$T_j=25^\circ C$ $T_j=150^\circ C$	5	5.8	6.5	V	
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		25	$T_j=25^\circ C$ $T_j=150^\circ C$	1.6	1.86 2.31	2.2	V	
Collector-emitter cut-off incl. diode	$I_{CES}$		0	1200		$T_j=25^\circ C$ $T_j=150^\circ C$			0.005	mA	
Gate-emitter leakage current	$I_{GES}$		20	0		$T_j=25^\circ C$ $T_j=150^\circ C$			200	nA	
Integrated gate resistor	$R_{gint}$							-		$\Omega$	
Turn-on delay time	$t_{d(on)}$	Rgon=32 $\Omega$ Rgoff=32 $\Omega$	$\pm 15$	600	25	$T_j=25^\circ C$		127		ns	
Rise time	$t_r$					$T_j=150^\circ C$		129			
Turn-off delay time	$t_{d(off)}$					$T_j=25^\circ C$		36			
Fall time	$t_f$					$T_j=150^\circ C$		41.8			
Turn-on energy loss per pulse	$E_{on}$					$T_j=25^\circ C$		232			
Turn-off energy loss per pulse	$E_{off}$	$T_j=150^\circ C$		276							
Input capacitance	$C_{ies}$	f=1MHz	0	25		$T_j=25^\circ C$		1430		pF	
Output capacitance	$C_{oss}$						$T_j=25^\circ C$		115		
Reverse transfer capacitance	$C_{rss}$								85		
Gate charge	$Q_{Gate}$	Vcc=960V	$\pm 15$		25	$T_j=25^\circ C$		200		nC	
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal foil thickness=76um						0.71		K/W	
Thermal resistance chip to case per chip	$R_{thJC}$	Kunze foil KU-ALF5						N/A			
<b>Brc Diode</b>											
Diode forward voltage	$V_F$				10	$T_j=25^\circ C$ $T_j=150^\circ C$	1.3	1.85 1.76	2.2	V	
Reverse leakage current	$I_r$		$\pm 15$	600	10	$T_j=25^\circ C$ $T_j=150^\circ C$			5	$\mu A$	
Peak reverse recovery current	$I_{RRM}$	Rgon=32 $\Omega$	$\pm 15$	600	10	$T_j=25^\circ C$		10.2		A	
Reverse recovery time	$t_{rr}$					$T_j=150^\circ C$		12.3			
Reverse recovered charge	$Q_{rr}$					$T_j=25^\circ C$		396			
						$T_j=150^\circ C$		624			
Peak rate of fall of recovery current	$di(rec)max/dt$					$T_j=25^\circ C$		1.55			
Reverse recovery energy	$E_{rec}$	$T_j=150^\circ C$		3.03							
		$T_j=25^\circ C$		36							
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal foil thickness=76um						1.62		K/W	
Thermal resistance chip to case per chip	$R_{thJC}$	Kunze foil KU-ALF5						N/A			
<b>Thermistor</b>											
Rated resistance	R					$T_j=25^\circ C$ $T_j=125^\circ C$	20.9	22 0.75	23.1	k $\Omega$	
Operating current	I					$T_j=25^\circ C$			0.3	mA	
Power dissipation	P					$T_j=25^\circ C$		200		mW	
B-value	$B_{(25/50)}$	Tol. $\pm 3\%$				$T_j=25^\circ C$		3950		K	

## Output Inverter

Figure 1 Output inverter IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

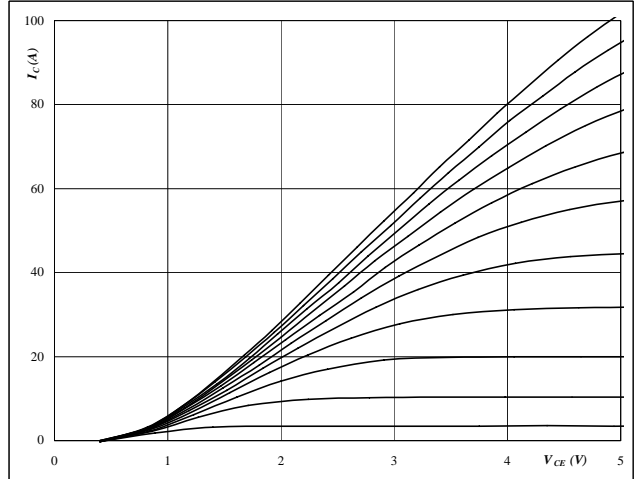


At  
 $t_p = 250 \mu s$   
 $T_j = 25 \text{ } ^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

Figure 2 Output inverter IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

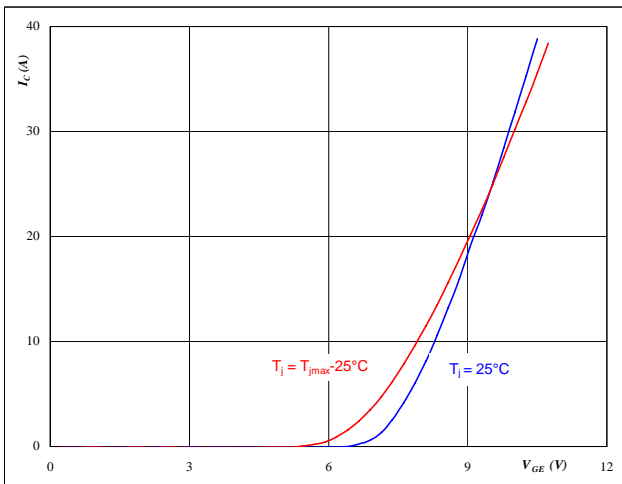


At  
 $t_p = 250 \mu s$   
 $T_j = 150 \text{ } ^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

Figure 3 Output inverter IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

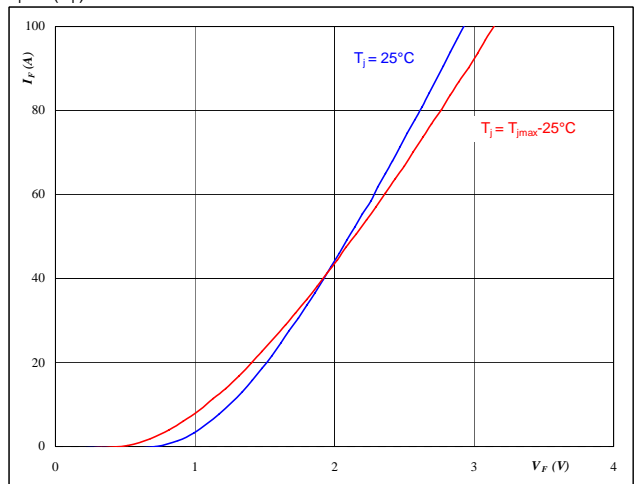


At  
 $t_p = 250 \mu s$   
 $V_{CE} = 10 V$

Figure 4 Output inverter FRED

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$

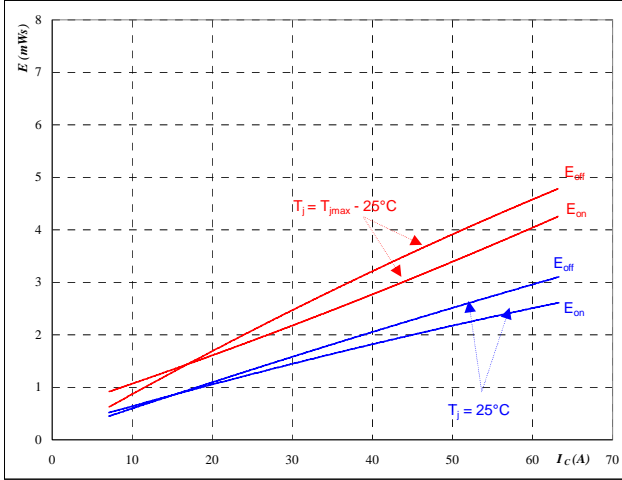


At  
 $t_p = 250 \mu s$

## Output Inverter

Figure 5 Output inverter IGBT

Typical switching energy losses  
as a function of collector current  
 $E = f(I_C)$

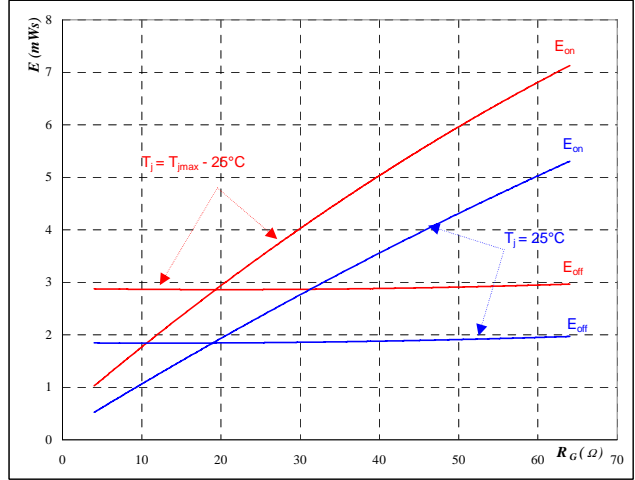


With an inductive load at

$T_j = 25/150 \text{ }^\circ\text{C}$   
 $V_{CE} = 600 \text{ V}$   
 $V_{GE} = \pm 15 \text{ V}$   
 $R_{gon} = 16 \text{ } \Omega$   
 $R_{goff} = 16 \text{ } \Omega$

Figure 6 Output inverter IGBT

Typical switching energy losses  
as a function of gate resistor  
 $E = f(R_G)$

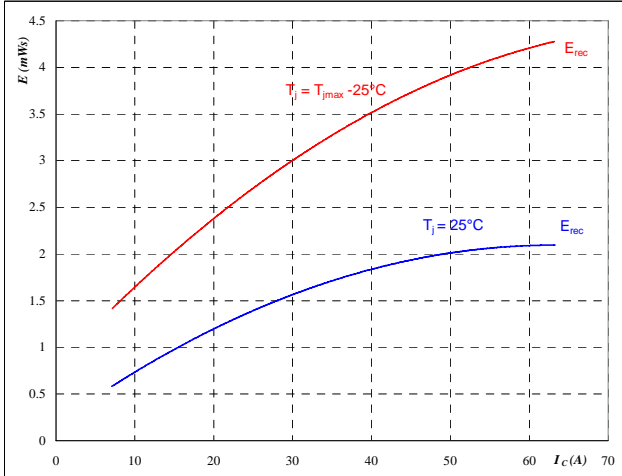


With an inductive load at

$T_j = 25/150 \text{ }^\circ\text{C}$   
 $V_{CE} = 600 \text{ V}$   
 $V_{GE} = \pm 15 \text{ V}$   
 $I_C = 35 \text{ A}$

Figure 7 Output inverter IGBT

Typical reverse recovery energy loss  
as a function of collector current  
 $E_{rec} = f(I_C)$

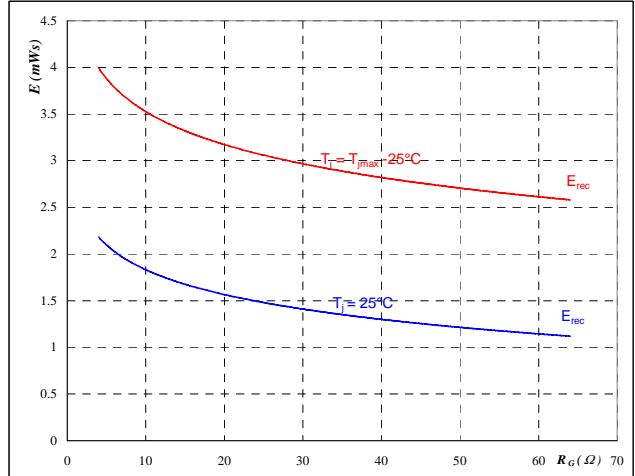


With an inductive load at

$T_j = 25/150 \text{ }^\circ\text{C}$   
 $V_{CE} = 600 \text{ V}$   
 $V_{GE} = \pm 15 \text{ V}$   
 $R_{gon} = 16 \text{ } \Omega$

Figure 8 Output inverter IGBT

Typical reverse recovery energy loss  
as a function of gate resistor  
 $E_{rec} = f(R_G)$



With an inductive load at

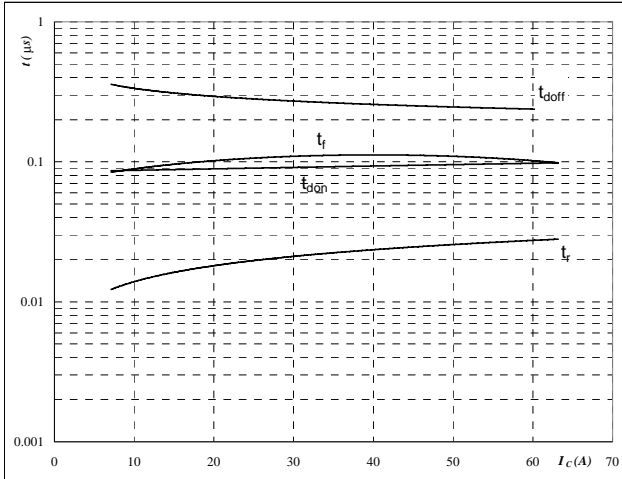
$T_j = 25/150 \text{ }^\circ\text{C}$   
 $V_{CE} = 600 \text{ V}$   
 $V_{GE} = \pm 15 \text{ V}$   
 $I_C = 35 \text{ A}$

## Output Inverter

Figure 9 Output inverter IGBT

Typical switching times as a function of collector current

$t = f(I_C)$



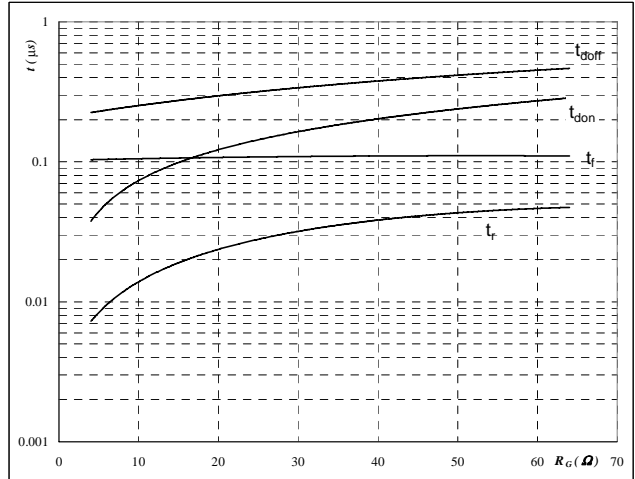
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	16	Ω
$R_{goff} =$	16	Ω

Figure 10 Output inverter IGBT

Typical switching times as a function of gate resistor

$t = f(R_G)$



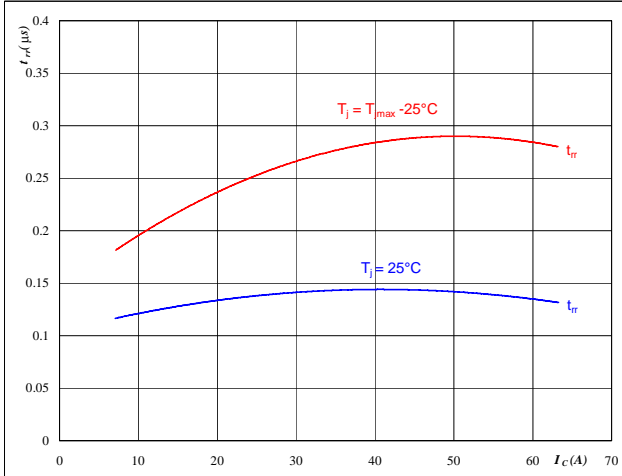
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	35	A

Figure 11 Output inverter FRED

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



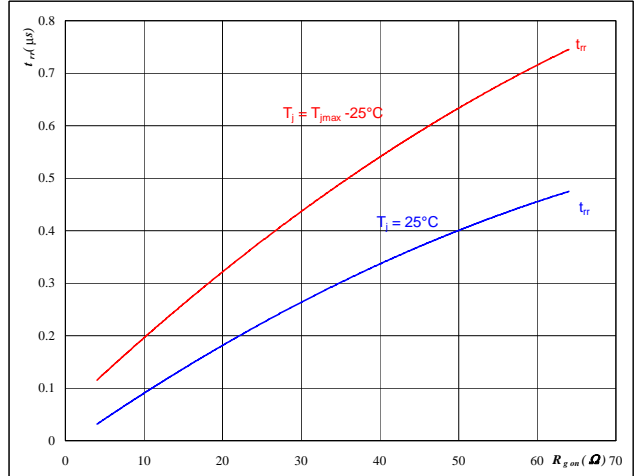
At

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	16	Ω

Figure 12 Output inverter FRED

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



At

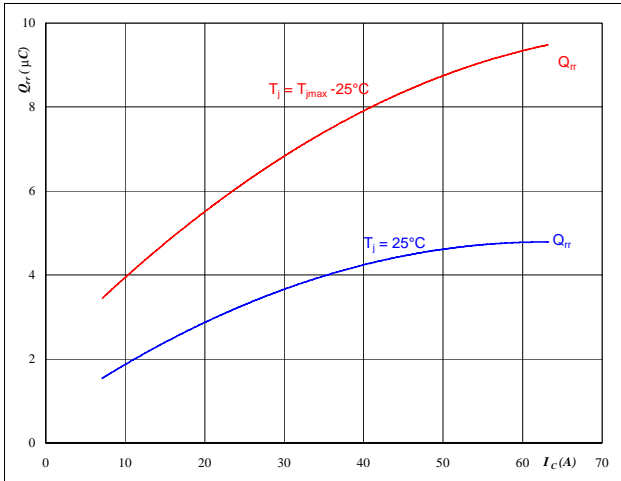
$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	35	A
$V_{GE} =$	±15	V

## Output Inverter

Figure 13 Output inverter FRED

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_c)$$



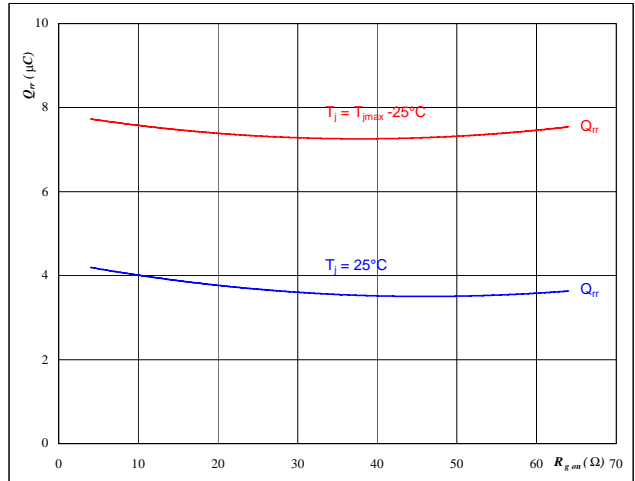
**At**

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	16	Ω

Figure 14 Output inverter FRED

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$



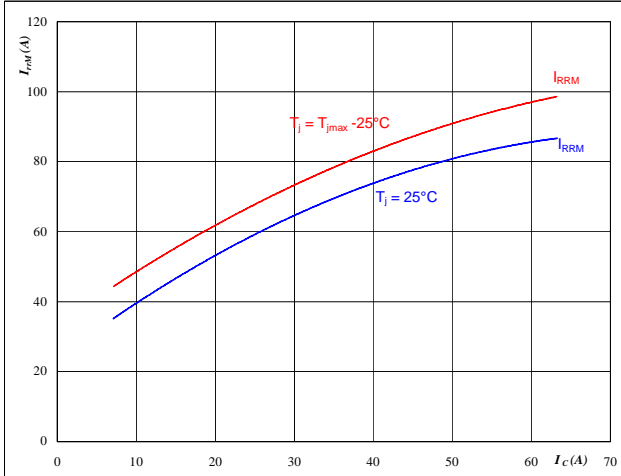
**At**

$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	35	A
$V_{GE} =$	±15	V

Figure 15 Output inverter FRED

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_c)$$



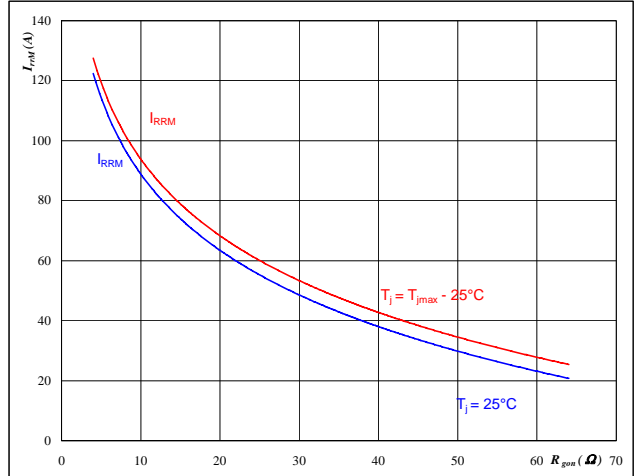
**At**

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	16	Ω

Figure 16 Output inverter FRED

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



**At**

$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	35	A
$V_{GE} =$	±15	V

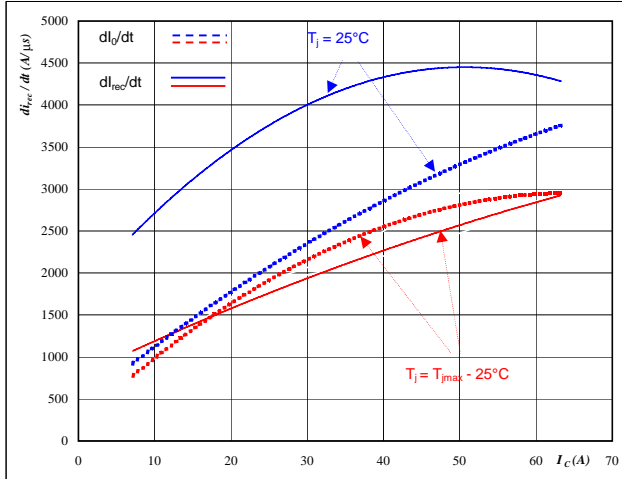


### Output Inverter

Figure 17 Output inverter FRED

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_o/dt, di_{rec}/dt = f(I_c)$



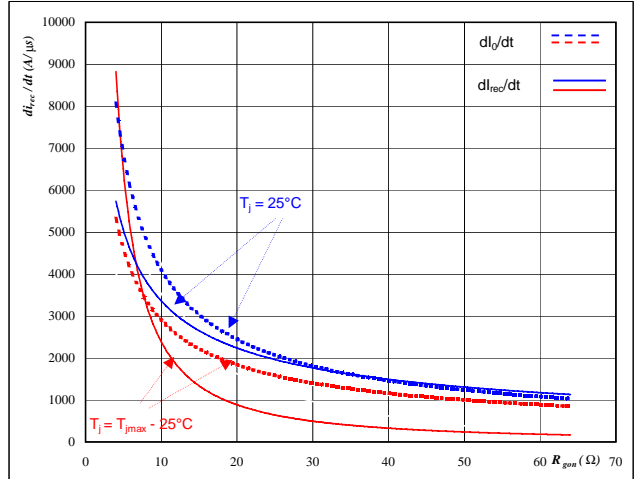
At

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	16	Ω

Figure 18 Output inverter FRED

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$di_o/dt, di_{rec}/dt = f(R_{gon})$



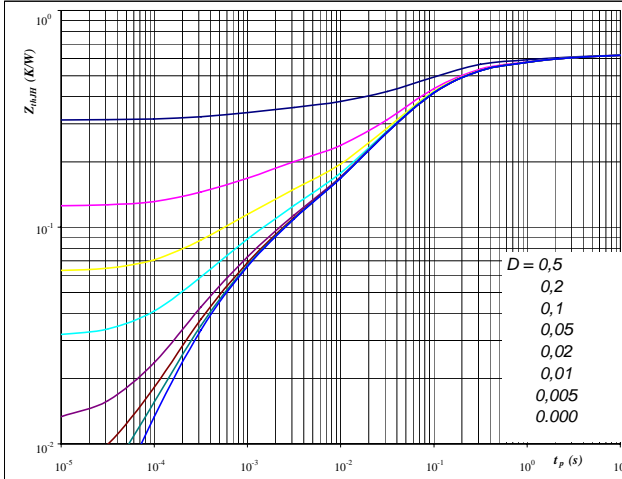
At

$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	35	A
$V_{GE} =$	±15	V

Figure 19 Output inverter IGBT

IGBT transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At

$D =$	$t_p / T$	
$R_{thJH} =$	0.62	K/W

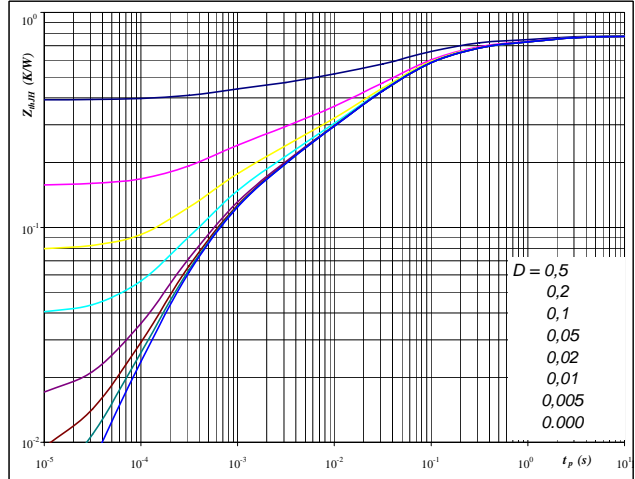
IGBT thermal model values

R (C/W)	Tau (s)
0.04	3.6E+00
0.09	5.8E-01
0.31	8.1E-02
0.09	1.7E-02
0.06	1.6E-03
0.03	2.8E-04

Figure 20 Output inverter FRED

FRED transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At

$D =$	$t_p / T$	
$R_{thJH} =$	0.78	K/W

FRED thermal model values

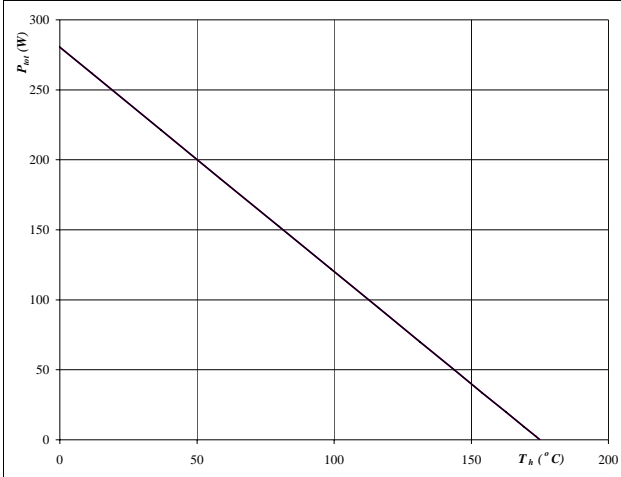
R (C/W)	Tau (s)
0.02	9.7E+00
0.09	9.8E-01
0.24	1.0E-01
0.22	2.5E-02
0.11	2.9E-03
0.09	4.1E-04

## Output Inverter

Figure 21 Output inverter IGBT

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

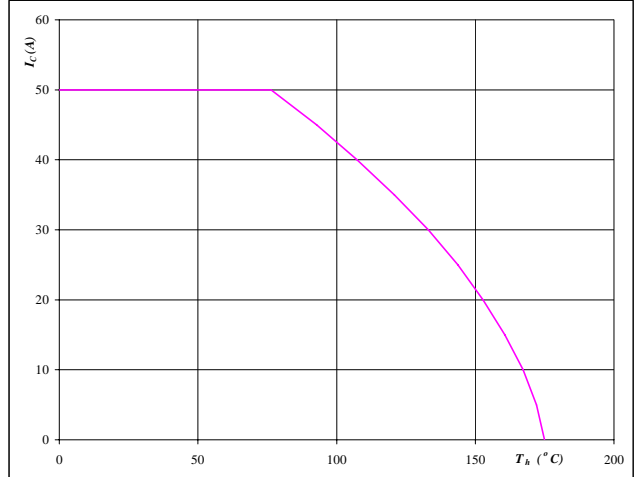


At  $T_j = 175$  °C  
— single heating  
— overall heating

Figure 22 Output inverter IGBT

Collector current as a function of heatsink temperature

$$I_C = f(T_h)$$

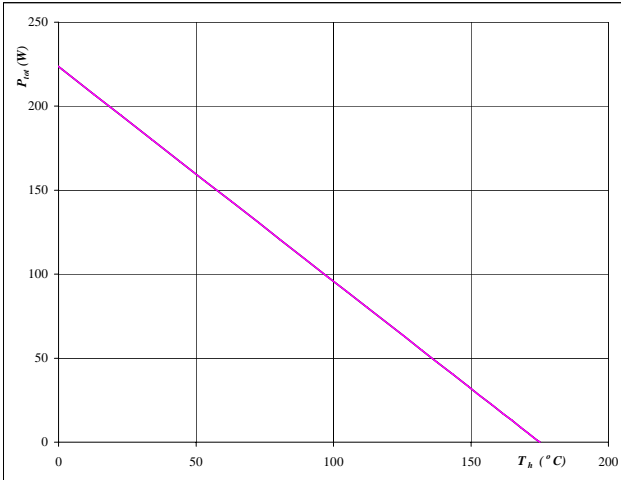


At  $T_j = 175$  °C  
 $V_{GE} = 15$  V

Figure 23 Output inverter FRED

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

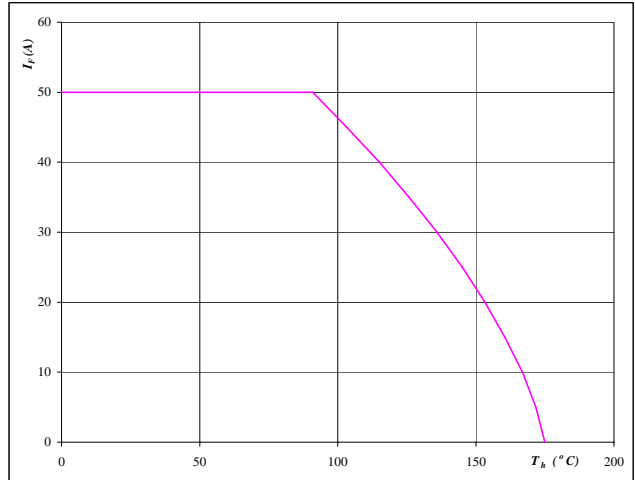


At  $T_j = 175$  °C  
— single heating  
— overall heating

Figure 24 Output inverter FRED

Forward current as a function of heatsink temperature

$$I_F = f(T_h)$$



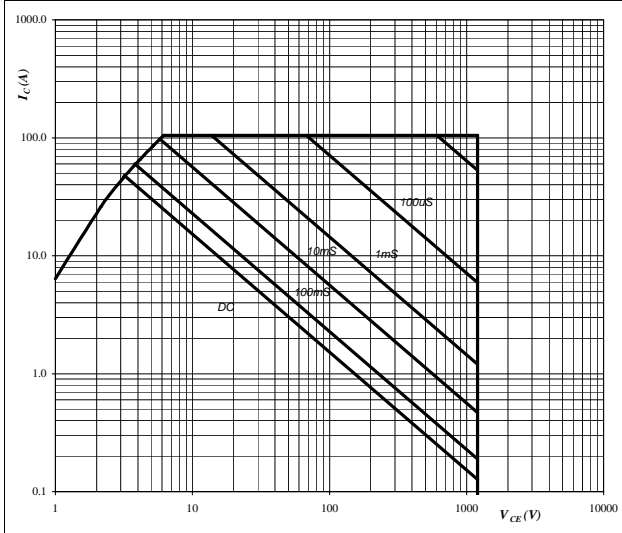
At  $T_j = 175$  °C

## Output Inverter

Figure 25 Output inverter IGBT

Safe operating area as a function of collector-emitter voltage

$$I_C = f(V_{CE})$$

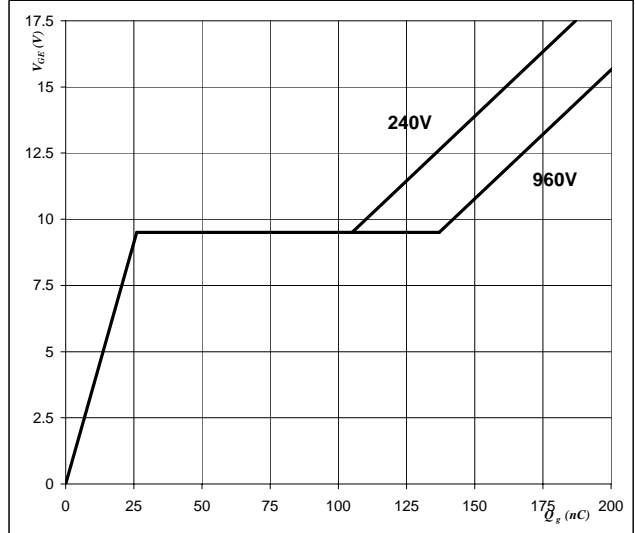


At  
 D = single pulse  
 Th = 80 °C  
 V<sub>GE</sub> = ±15 V  
 T<sub>j</sub> = T<sub>jmax</sub> °C

Figure 26 Output inverter IGBT

Gate voltage vs Gate charge

$$V_{GE} = f(Q_g)$$



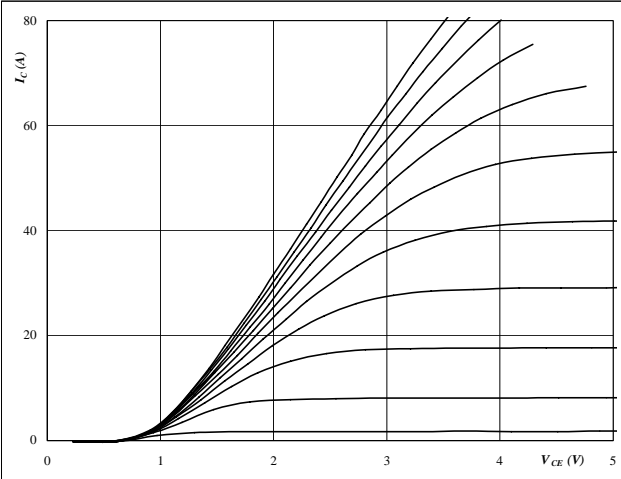
At  
 I<sub>C</sub> = 35 A

# Brake

Figure 1 Brake IGBT

Typical output characteristics

$I_C = f(V_{CE})$

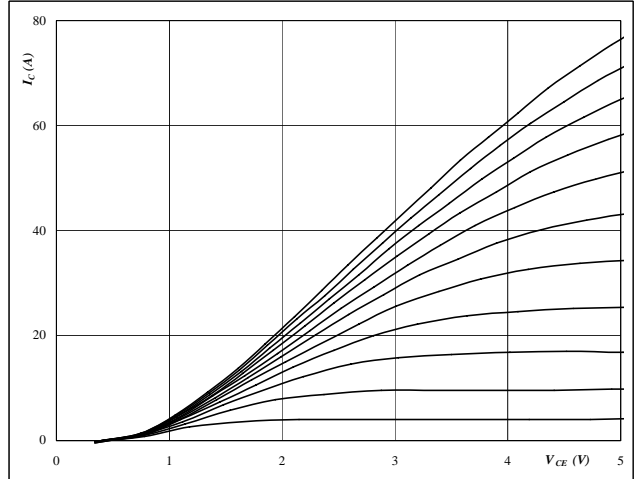


At  
 $t_p = 250 \mu s$   
 $T_j = 25 \text{ }^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

Figure 2 Brake IGBT

Typical output characteristics

$I_C = f(V_{CE})$

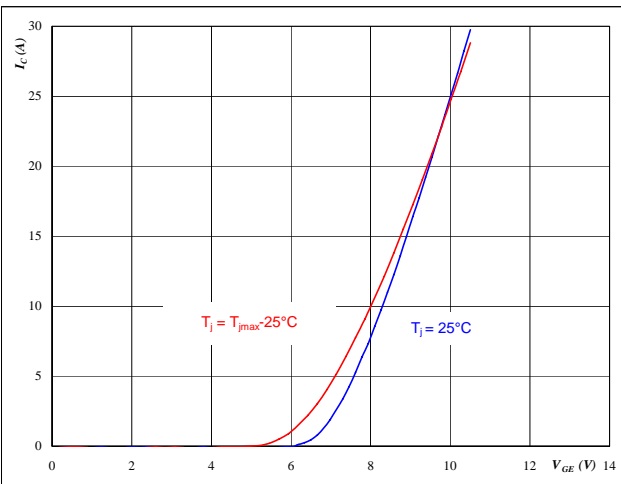


At  
 $t_p = 250 \mu s$   
 $T_j = 150 \text{ }^\circ C$   
 $V_{GE}$  from 7 V to 17 V in steps of 1 V

Figure 3 Brake IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$

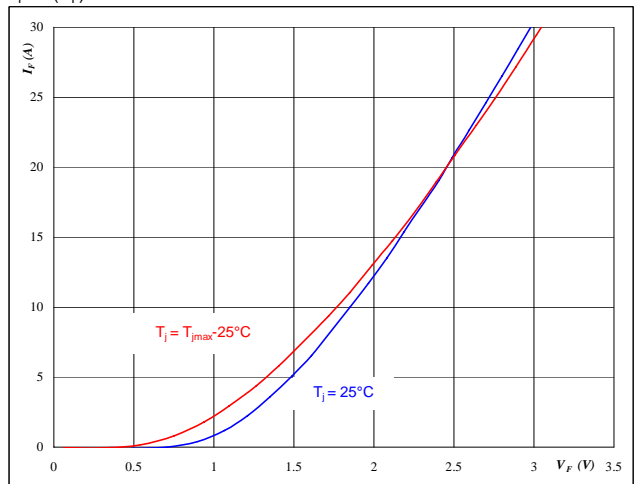


At  
 $t_p = 250 \mu s$   
 $V_{CE} = 10 V$

Figure 4 Brake FRED

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



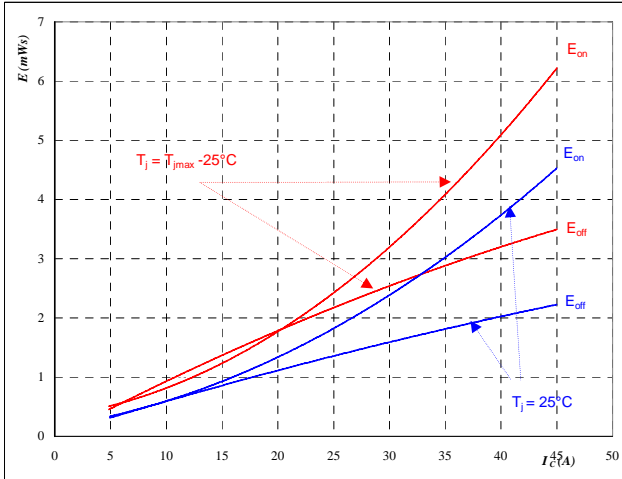
At  
 $t_p = 250 \mu s$

# Brake

Figure 5 Brake IGBT

Typical switching energy losses  
as a function of collector current

$E = f(I_C)$



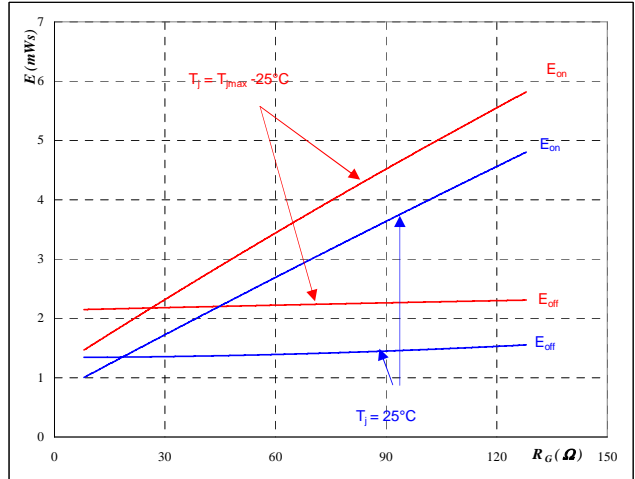
With an inductive load at

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	32	Ω
$R_{goff} =$	32	Ω

Figure 6 Brake IGBT

Typical switching energy losses  
as a function of gate resistor

$E = f(R_G)$



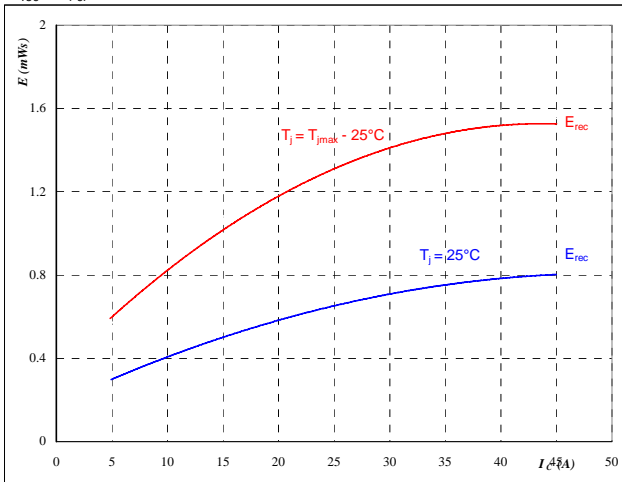
With an inductive load at

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	25	A

Figure 7 Brake IGBT

Typical reverse recovery energy loss  
as a function of collector current

$E_{rec} = f(I_C)$



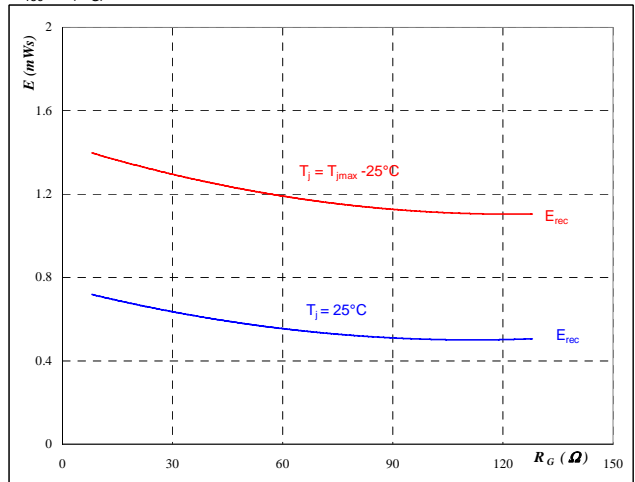
With an inductive load at

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	32	Ω

Figure 8 Brake IGBT

Typical reverse recovery energy loss  
as a function of gate resistor

$E_{rec} = f(R_G)$



With an inductive load at

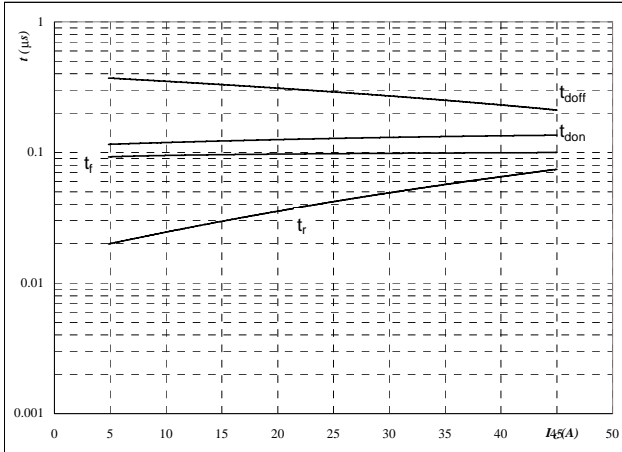
$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	25	A

## Brake

Figure 9 Brake IGBT

Typical switching times as a function of collector current

$t = f(I_C)$



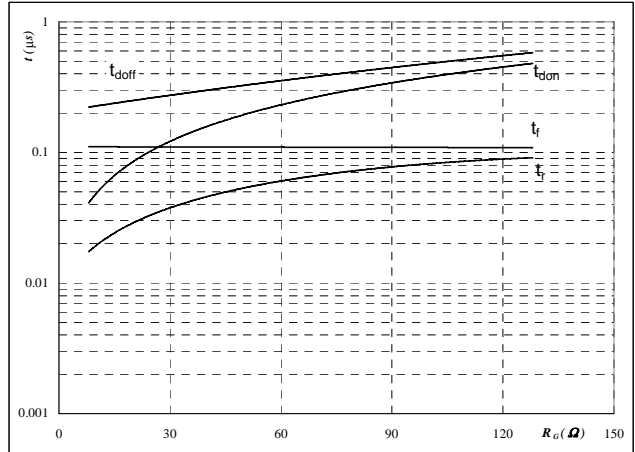
With an inductive load at

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	32	Ω
$R_{goff} =$	32	Ω

Figure 10 Brake IGBT

Typical switching times as a function of gate resistor

$t = f(R_G)$



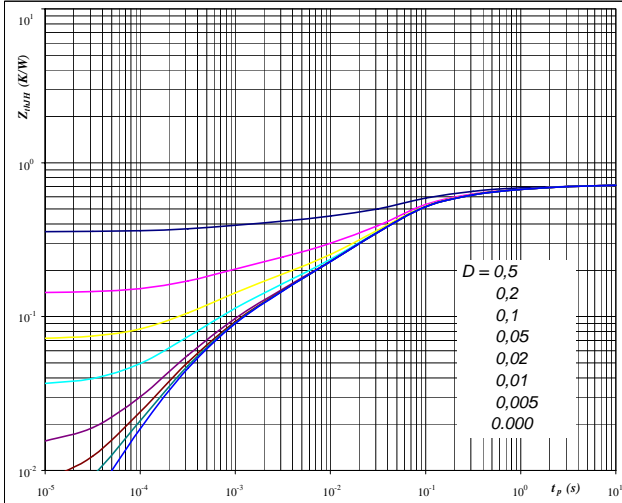
With an inductive load at

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	25	A

Figure 11 Brake IGBT

IGBT transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



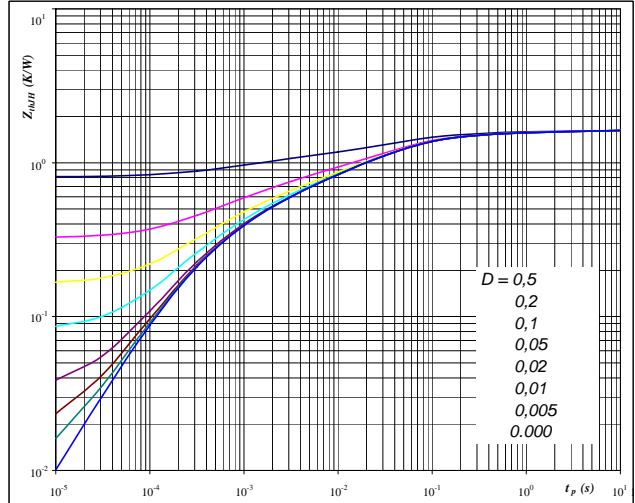
At

$D =$	$t_p / T$	
$R_{thJH} =$	0.71	K/W

Figure 12 Brake FRED

FRED transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At

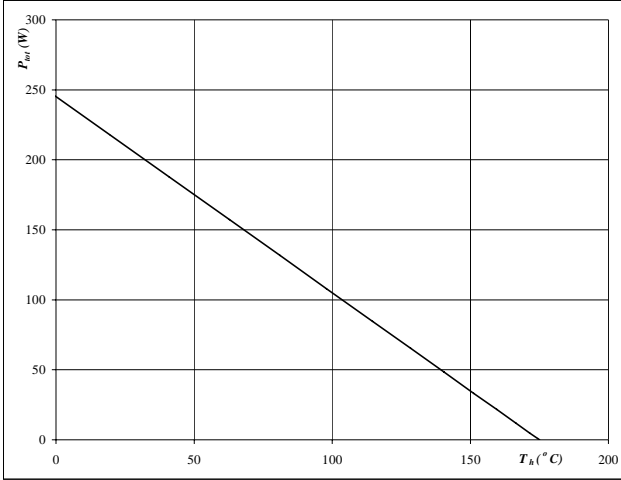
$D =$	$t_p / T$	
$R_{thJH} =$	1.62	K/W

# Brake

Figure 13 Brake IGBT

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

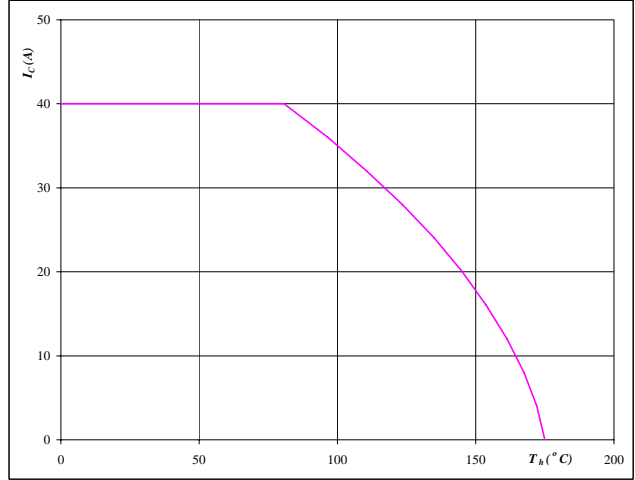


At  
 $T_j = 175 \text{ °C}$

Figure 14 Brake IGBT

Collector current as a function of heatsink temperature

$$I_C = f(T_h)$$

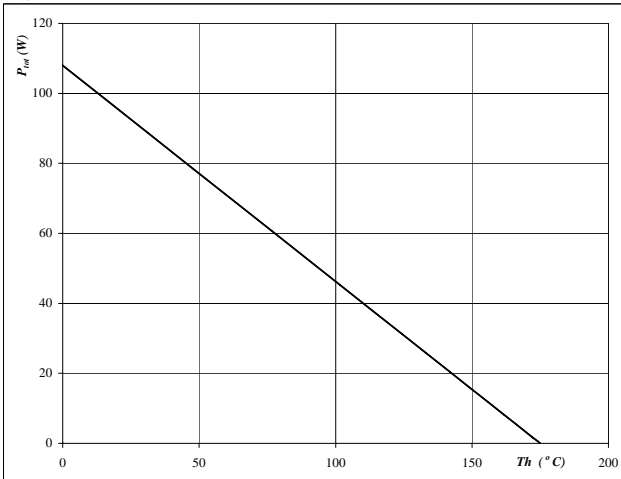


At  
 $T_j = 175 \text{ °C}$   
 $V_{GE} = 15 \text{ V}$

Figure 15 Brake FRED

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

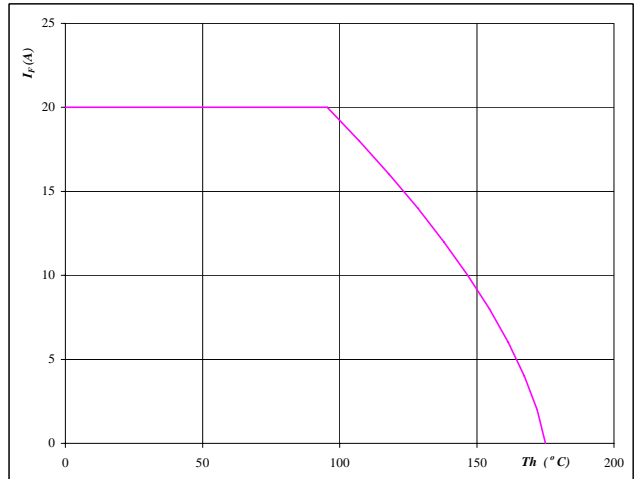


At  
 $T_j = 175 \text{ °C}$

Figure 16 Brake FRED

Forward current as a function of heatsink temperature

$$I_F = f(T_h)$$



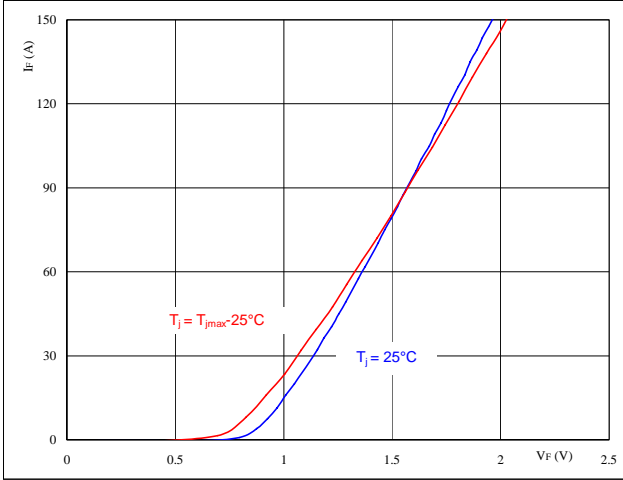
At  
 $T_j = 175 \text{ °C}$

### Input Rectifier Bridge

Figure 1 Rectifier diode

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$

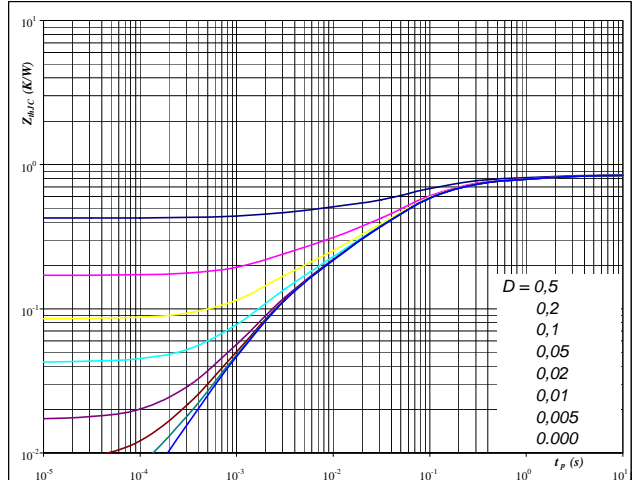


At  
 $t_p = 250 \mu s$

Figure 2 Rectifier diode

Diode transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$

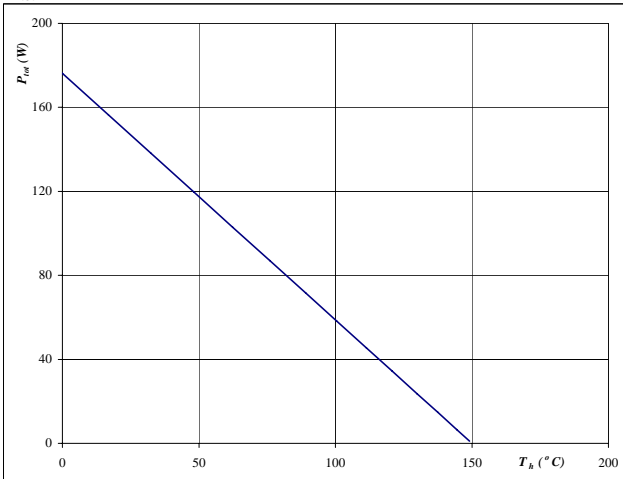


At  
 $D = t_p / T$   
 $R_{thJH} = 0.851 \text{ K/W}$

Figure 3 Rectifier diode

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$

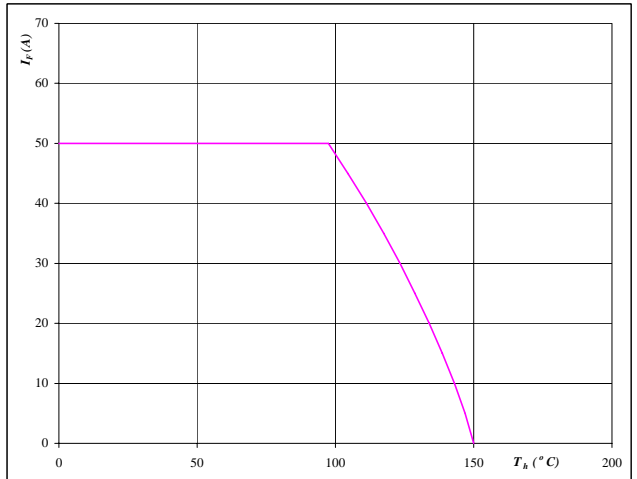


At  
 $T_j = 150 \text{ }^\circ\text{C}$

Figure 4 Rectifier diode

Forward current as a function of heatsink temperature

$I_F = f(T_h)$



At  
 $T_j = 150 \text{ }^\circ\text{C}$

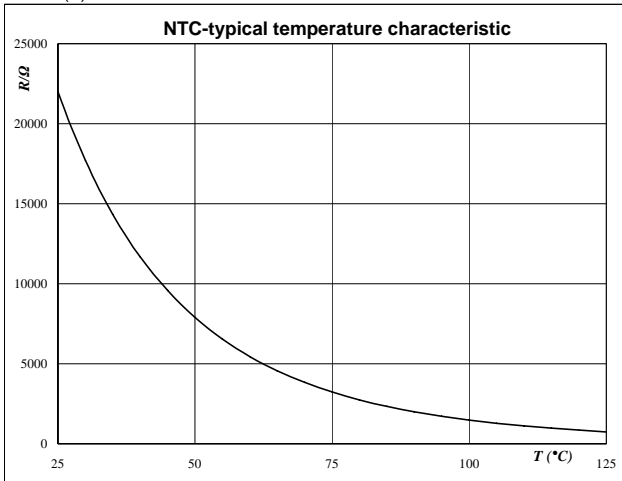


## Thermistor

Figure 1 Thermistor

Typical NTC characteristic  
as a function of temperature

$$R_T = f(T)$$



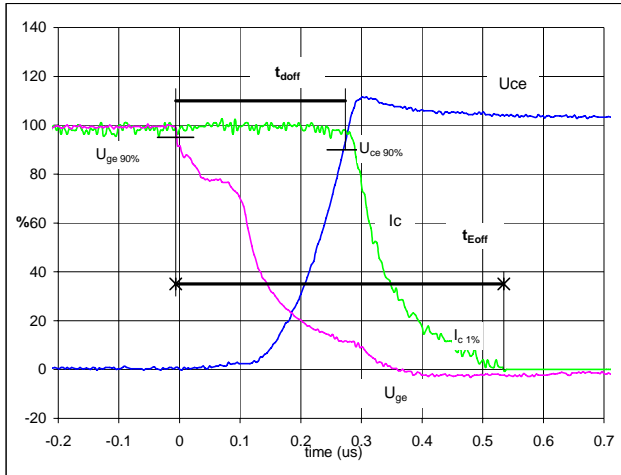
## Switching Definitions Output Inverter

General conditions

$T_j$	=	150 °C
$R_{gon}$	=	16 $\Omega$
$R_{goff}$	=	16 $\Omega$

Figure 1 Output inverter IGBT

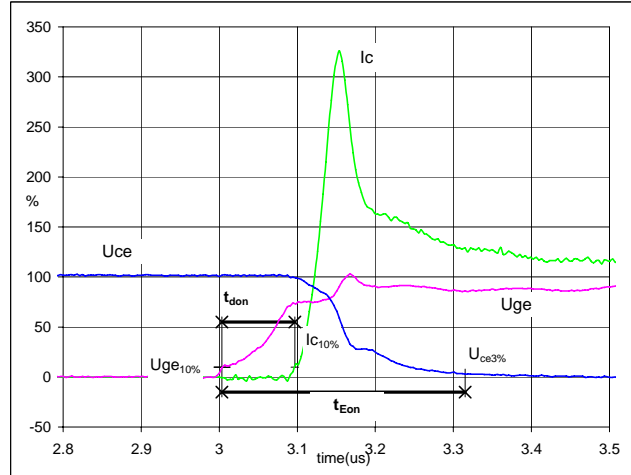
Turn-off Switching Waveforms & definition of  $t_{doff}$ ,  $t_{Eoff}$   
( $t_{Eoff}$  = integrating time for  $E_{off}$ )



$V_{GE}$ (0%) =	-15	V
$V_{GE}$ (100%) =	15	V
$V_C$ (100%) =	600	V
$I_C$ (100%) =	35	A
$t_{doff}$ =	0.27	$\mu$ s
$t_{Eoff}$ =	0.54	$\mu$ s

Figure 2 Output inverter IGBT

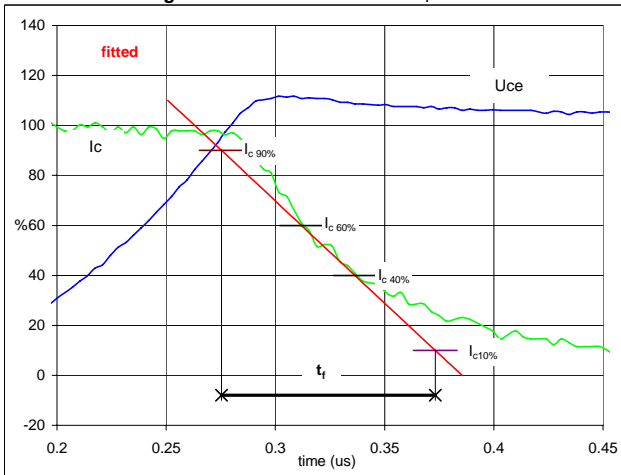
Turn-on Switching Waveforms & definition of  $t_{don}$ ,  $t_{Eon}$   
( $t_{Eon}$  = integrating time for  $E_{on}$ )



$V_{GE}$ (0%) =	-15	V
$V_{GE}$ (100%) =	15	V
$V_C$ (100%) =	600	V
$I_C$ (100%) =	35	A
$t_{don}$ =	0.09	$\mu$ s
$t_{Eon}$ =	0.31	$\mu$ s

Figure 3 Output inverter IGBT

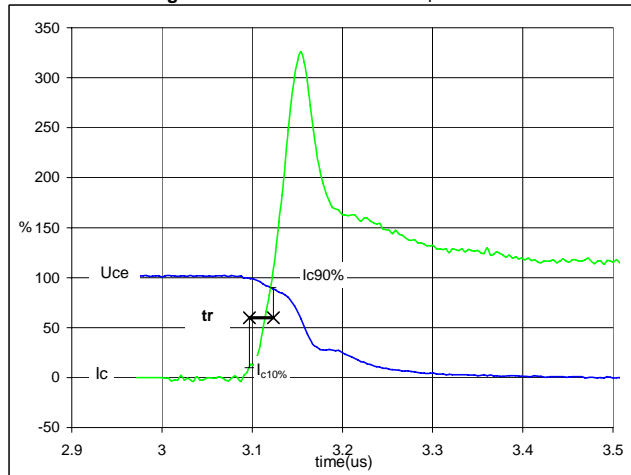
Turn-off Switching Waveforms & definition of  $t_f$



$V_C$ (100%) =	600	V
$I_C$ (100%) =	35	A
$t_f$ =	0.11	$\mu$ s

Figure 4 Output inverter IGBT

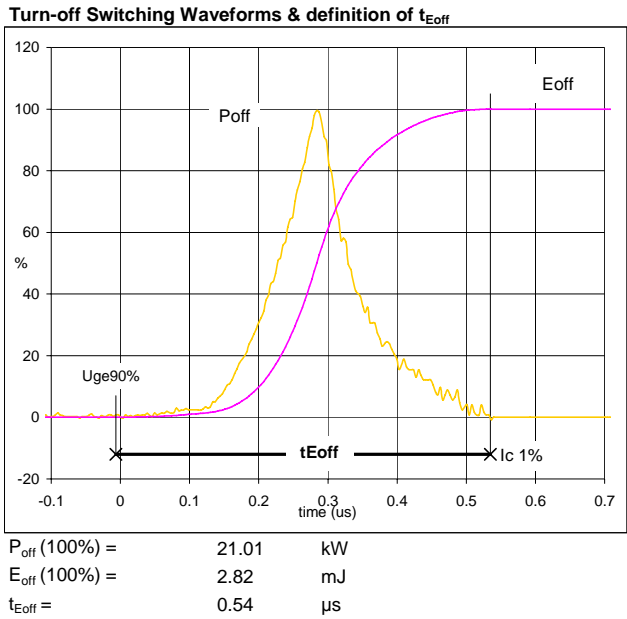
Turn-on Switching Waveforms & definition of  $t_r$



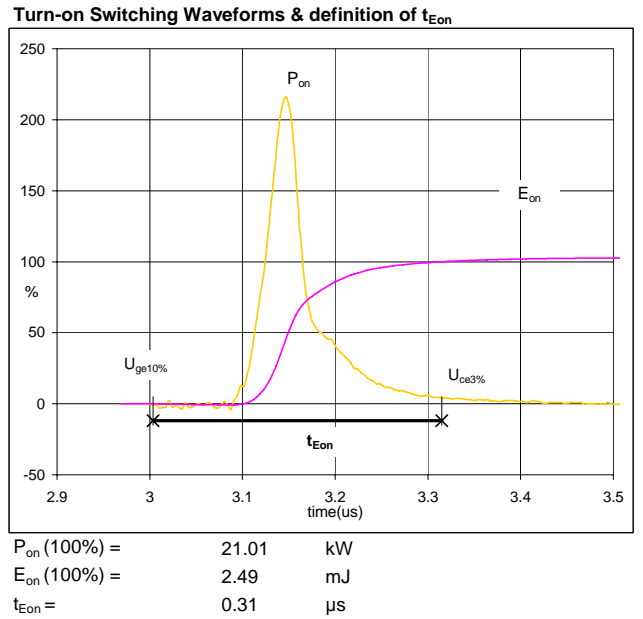
$V_C$ (100%) =	600	V
$I_C$ (100%) =	35	A
$t_r$ =	0.02	$\mu$ s

## Switching Definitions Output Inverter

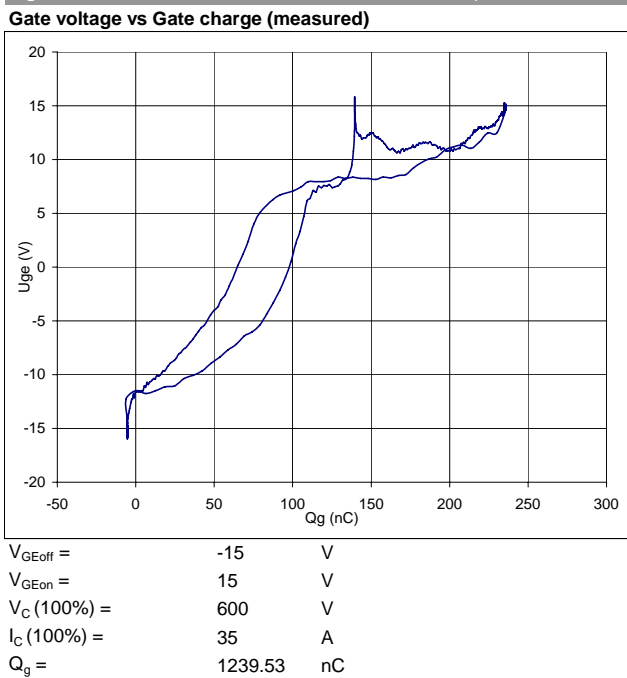
**Figure 5** Output inverter IGBT



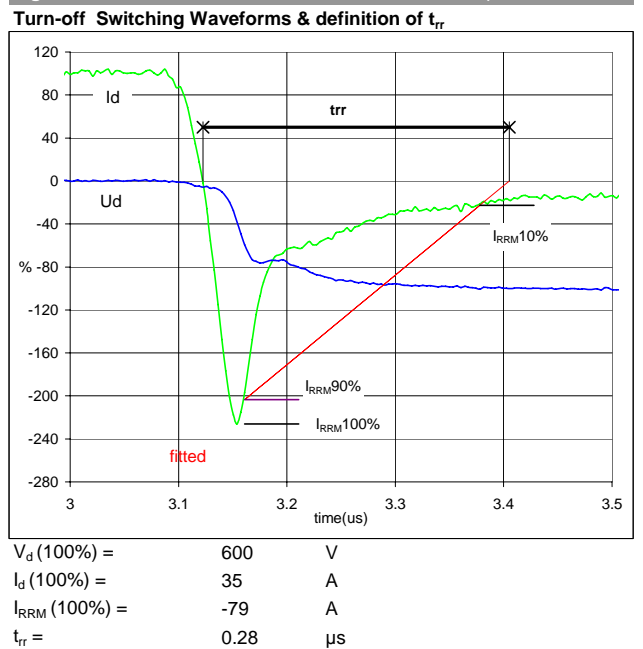
**Figure 6** Output inverter IGBT



**Figure 7** Output inverter FRED



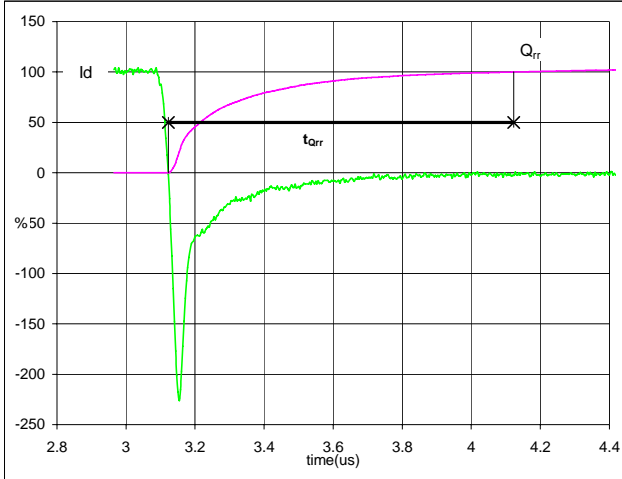
**Figure 8** Output inverter IGBT



## Switching Definitions Output Inverter

**Figure 9** Output inverter FRED

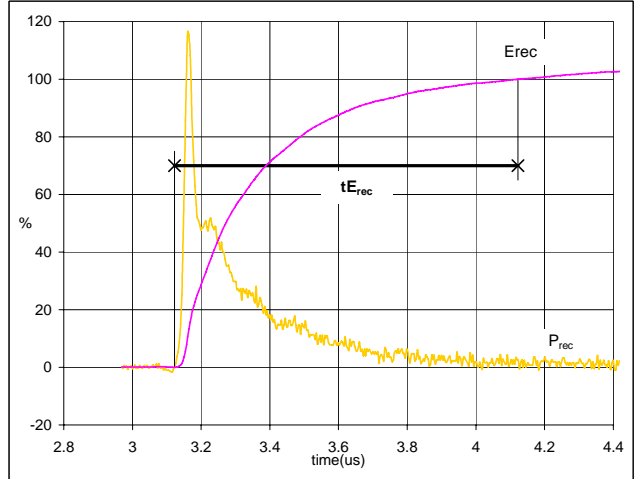
Turn-on Switching Waveforms & definition of  $t_{Qrr}$   
( $t_{Qrr}$  = integrating time for  $Q_{rr}$ )



$I_d$ (100%) =	35	A
$Q_{rr}$ (100%) =	7.47	$\mu\text{C}$
$t_{Qrr}$ =	1.00	$\mu\text{s}$

**Figure 10** Output inverter FRED

Turn-on Switching Waveforms & definition of  $t_{Erec}$   
( $t_{Erec}$  = integrating time for  $E_{rec}$ )



$P_{rec}$ (100%) =	21.01	kW
$E_{rec}$ (100%) =	3.31	mJ
$t_{Erec}$ =	1.00	$\mu\text{s}$

General conditions

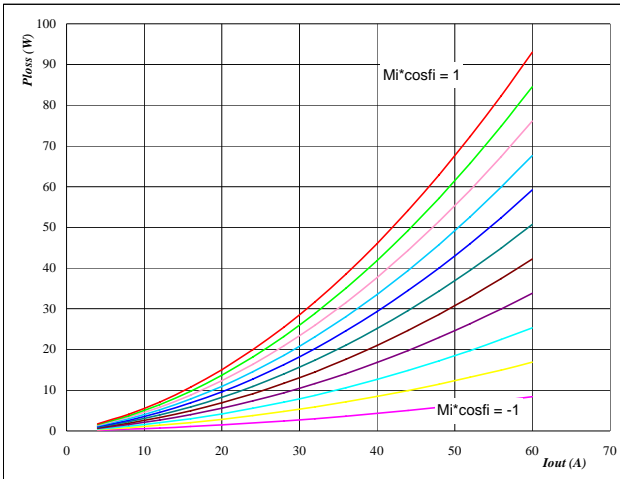
3phase SPWM

$V_{GEon} = 15\text{ V}$   
 $V_{GEoff} = -15\text{ V}$   
 $R_{gon} = 16\ \Omega$   
 $R_{goff} = 16\ \Omega$

Figure 1 IGBT

Typical average static loss as a function of output current

$P_{loss} = f(I_{out})$

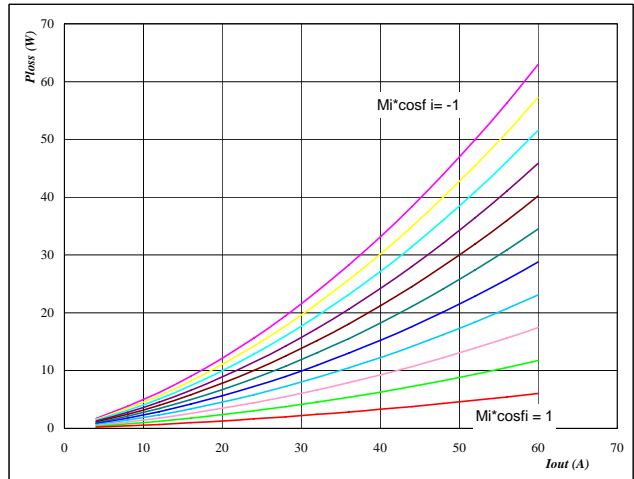


At  
 $T_j = 150\ \text{°C}$   
 $M_i \cdot \cos\phi$  from -1 to 1 in steps of 0.2

Figure 2 FRED

Typical average static loss as a function of output current

$P_{loss} = f(I_{out})$

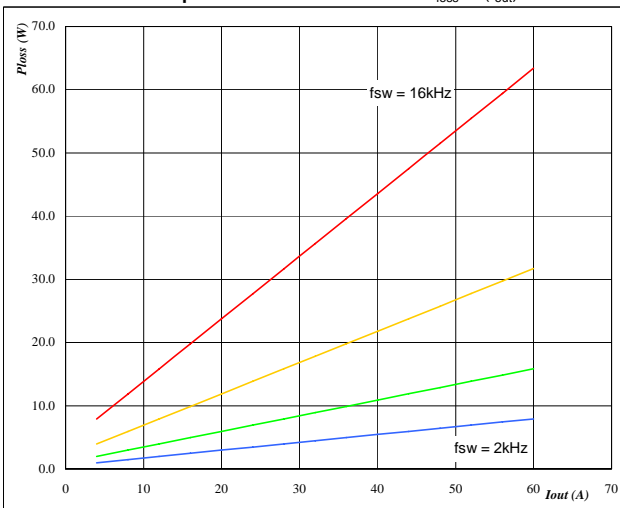


At  
 $T_j = 150\ \text{°C}$   
 $M_i \cdot \cos\phi$  from -1 to 1 in steps of 0.2

Figure 3 IGBT

Typical average switching loss as a function of output current

$P_{loss} = f(I_{out})$

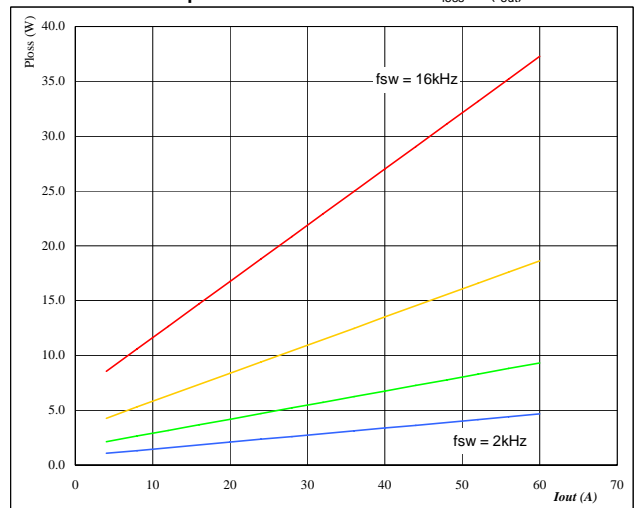


At  
 $T_j = 150\ \text{°C}$   
 DC link = 600 V  
 $f_{sw}$  from 2 kHz to 16 kHz in steps of factor 2

Figure 4 FRED

Typical average switching loss as a function of output current

$P_{loss} = f(I_{out})$

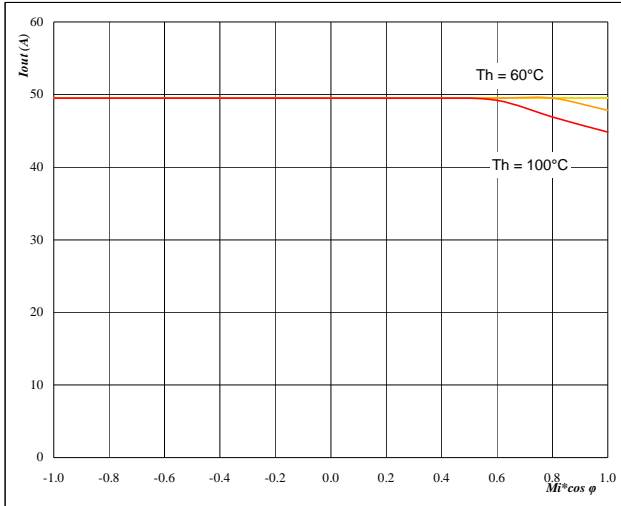


At  
 $T_j = 150\ \text{°C}$   
 DC link = 600 V  
 $f_{sw}$  from 2 kHz to 16 kHz in steps of factor 2

Figure 5 Phase

Typical available 50Hz output current as a function  $Mi \cdot \cos \phi$

$$I_{out} = f(Mi \cdot \cos \phi)$$

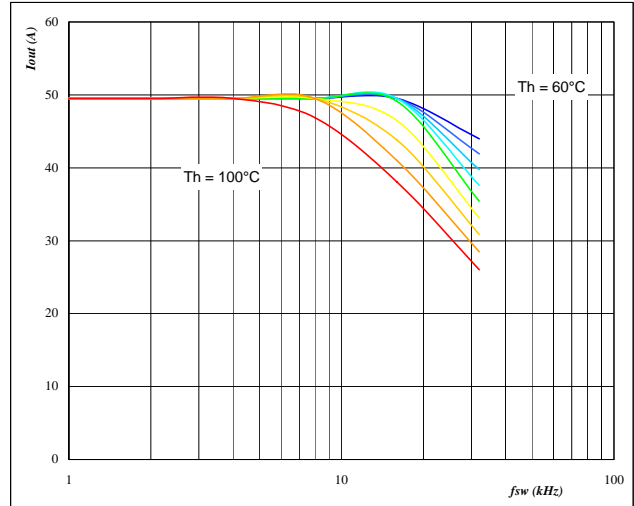


**At**  
 $T_j = 150^\circ\text{C}$   
 DC link = 600 V  
 $f_{sw} = 8$  kHz  
 $T_h$  from 60 °C to 100 °C in steps of 5 °C

Figure 6 Phase

Typical available 50Hz output current as a function of switching frequency

$$I_{out} = f(f_{sw})$$

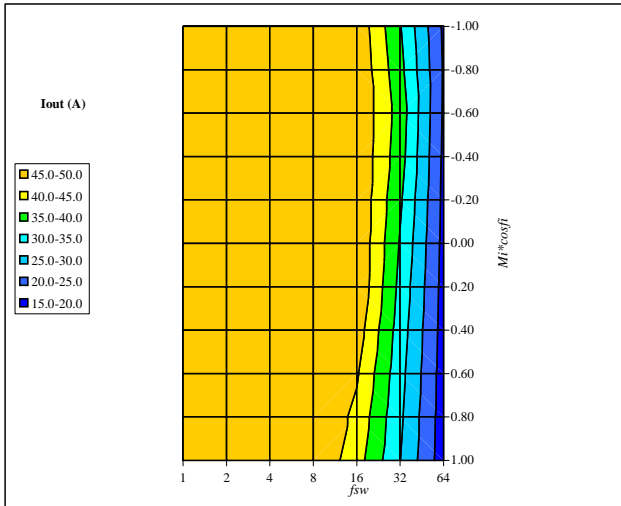


**At**  
 $T_j = 150^\circ\text{C}$   
 DC link = 600 V  
 $Mi \cdot \cos \phi = 0.8$   
 $T_h$  from 60 °C to 100 °C in steps of 5 °C

Figure 7 Phase

Typical available 50Hz output current as a function of  $Mi \cdot \cos \phi$  and switching frequency

$$I_{out} = f(f_{sw}, Mi \cdot \cos \phi)$$

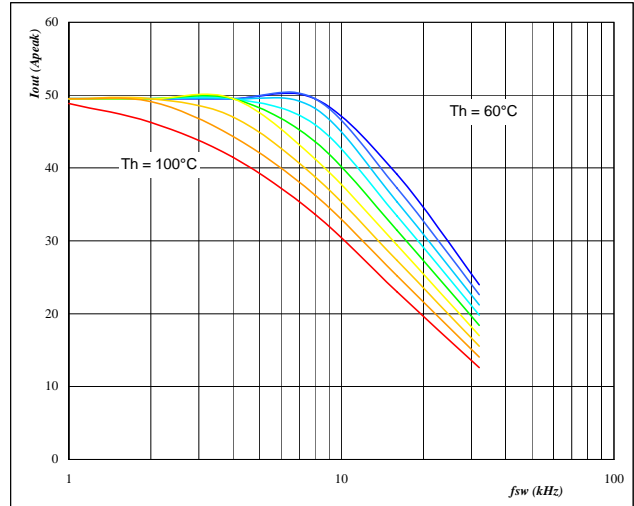


**At**  
 $T_j = 150^\circ\text{C}$   
 DC link = 600 V  
 $T_h = 90^\circ\text{C}$

Figure 8 Phase

Typical available 0Hz output current as a function of switching frequency

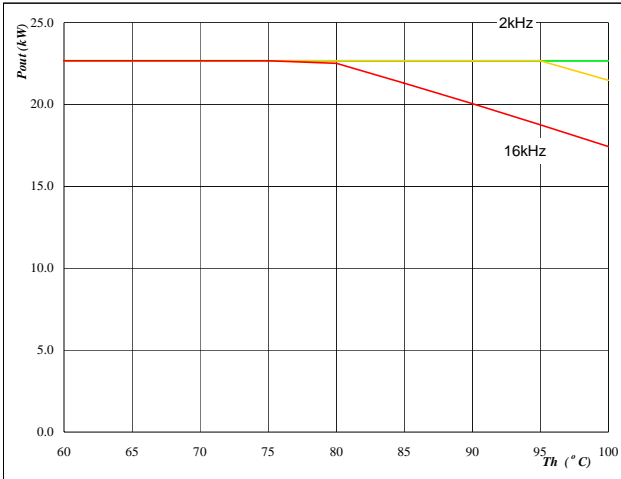
$$I_{outpeak} = f(f_{sw})$$



**At**  
 $T_j = 150^\circ\text{C}$   
 DC link = 600 V  
 $T_h$  from 60 °C to 100 °C in steps of 5 °C  
 $Mi = 0$

**Figure 9** Inverter

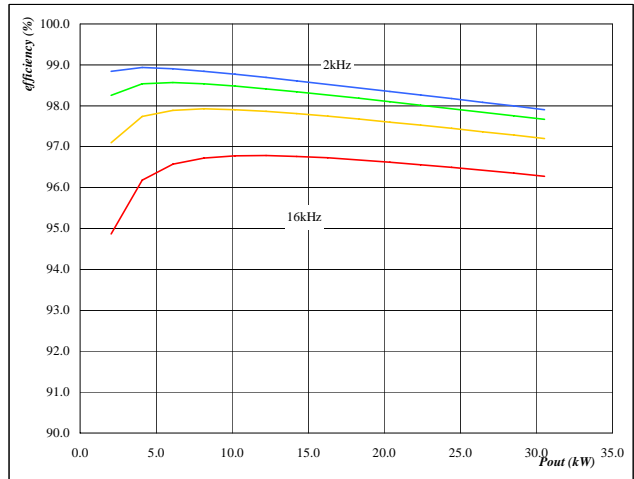
Typical available peak output power as a function of heatsink temperature  
 $P_{out}=f(T_h)$



**At**  
 $T_j = 150 \text{ } ^\circ\text{C}$   
 DC link = 600 V  
 $M_i = 1$   
 $\cos \varphi = 0.80$   
 $f_{sw}$  from 2 kHz to 16 kHz in steps of factor 2

**Figure 10** Inverter

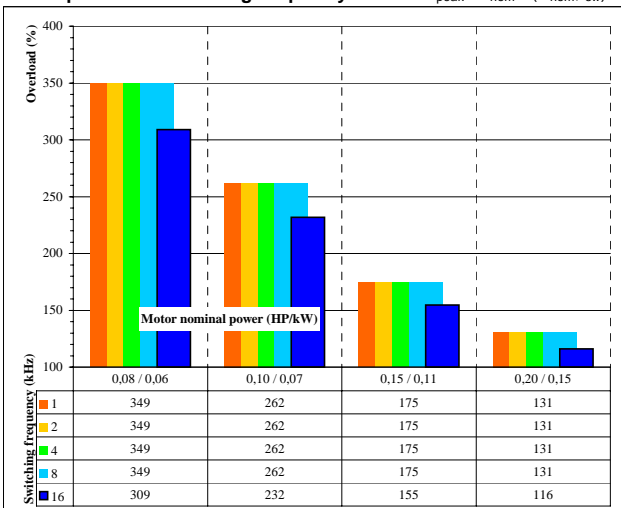
Typical efficiency as a function of output power  
efficiency=f( $P_{out}$ )



**At**  
 $T_j = 150 \text{ } ^\circ\text{C}$   
 DC link = 600 V  
 $M_i = 1$   
 $\cos \varphi = 0.80$   
 $f_{sw}$  from 2 kHz to 16 kHz in steps of factor 2

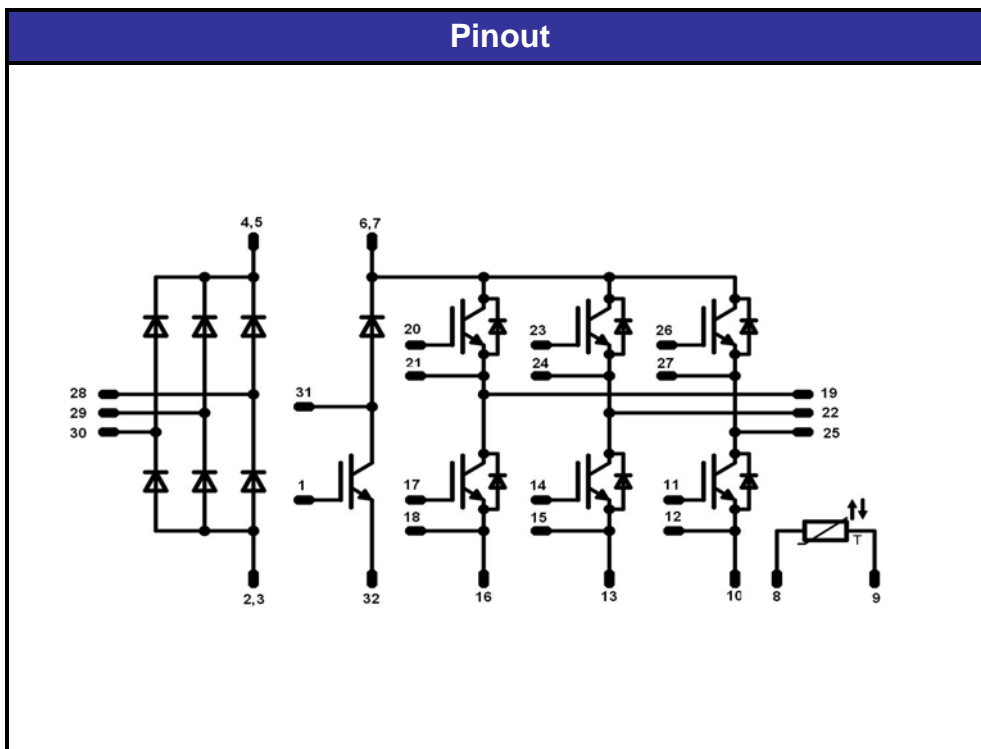
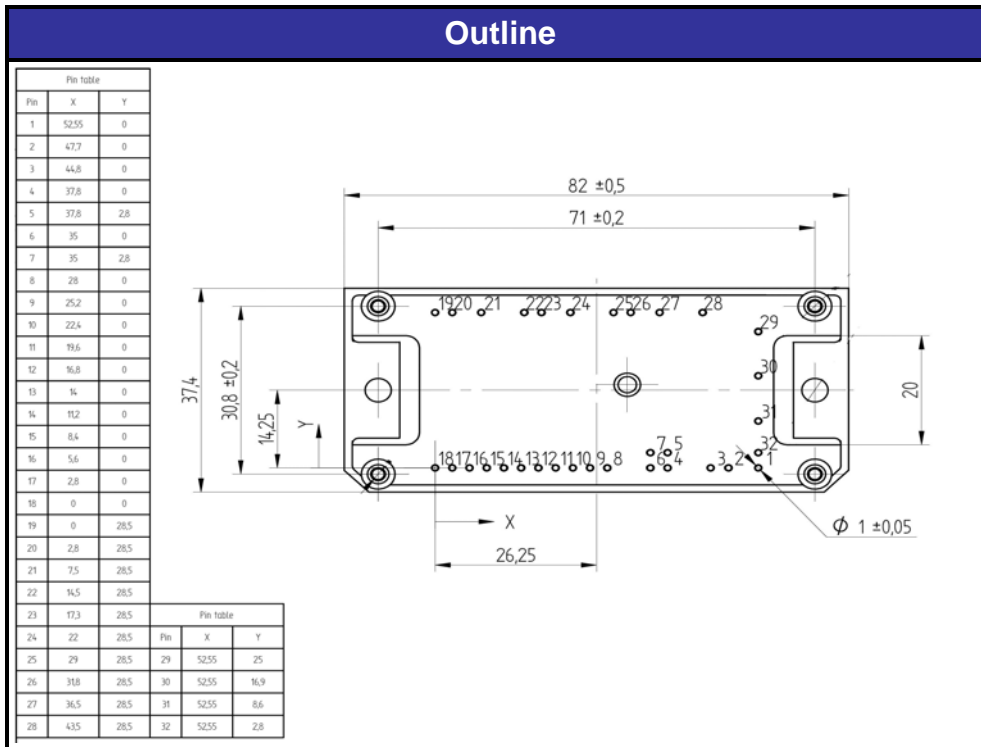
**Figure 11** Inverter

Typical available overload factor as a function of motor power and switching frequency  
 $P_{peak} / P_{nom}=f(P_{nom}, f_{sw})$



**At**  
 $T_j = 150 \text{ } ^\circ\text{C}$   
 DC link = 600 V  
 $M_i = 1$   
 $\cos \varphi = 0.8$   
 $f_{sw}$  from 1 kHz to 16kHz in steps of factor 2  
 $T_h = 90 \text{ } ^\circ\text{C}$   
 Motor eff = 0.85

Package Outline and Pinout





**PRODUCT STATUS DEFINITIONS**

<b>Datasheet Status</b>	<b>Product Status</b>	<b>Definition</b>
Target	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. The data contained is exclusively intended for technically trained staff.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data may be published at a later date. Vincotech reserves the right to make changes at any time without notice in order to improve design. The data contained is exclusively intended for technically trained staff.
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As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.